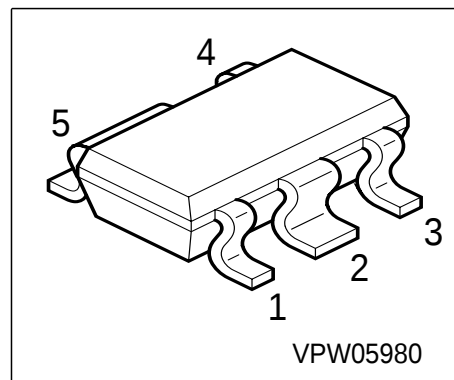


Silicon Switching Diode

Preliminary data

- Switching applications
- High breakdown voltage



Type	Marking	Ordering Code	Pin Configuration					Package
BAW 78M	GDs	Q62702-A3471	1 = A	2 = C	3 n.c.	4 n.c.	5 = C	SCT-595

Maximum Ratings

Parameter	Symbol	Values	Unit
Diode reverse voltage	V_R	400	V
Peak reverse voltage	V_{RM}	400	
Forward current	I_F	1	A
Peak forward current	I_{FM}	1	
Surge forward current, $t = 1 \mu s$	I_{FS}	10	
Total power dissipation, $T_S \leq 110^\circ C$	P_{tot}	1	W
Junction temperature	T_j	150	$^\circ C$
Storage temperature	T_{stg}	- 65 ...+150	

Thermal Resistance

Junction - ambient ¹⁾	R_{thJA}	≤ 95	K/W
Junction - soldering point	R_{thJS}	≤ 40	

1) Package mounted on epoxy pcb 40mm x 40mm x 1.5mm / 6cm² Cu

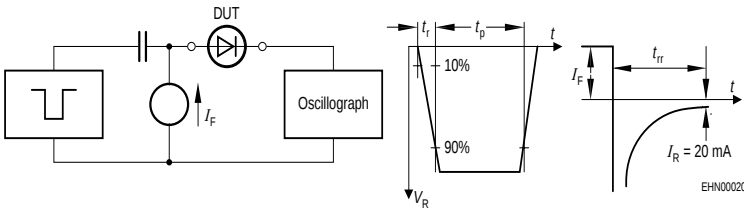
Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified.

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC characteristics					
Breakdown voltage $I_{(BR)} = 100\ \mu\text{A}$	$V_{(BR)}$	400	-	-	V
Forward voltage $I_F = 1\ \text{A}$	V_F	-	-	1.6	
$I_F = 2\ \text{A}$		-	-	2	
Reverse current $V_R = 400\ \text{V}$	I_R	-	-	1	μA
Reverse current $V_R = 400\ \text{V},\ T_A = 150\ ^\circ\text{C}$	I_R	-	-	50	

AC characteristics

Diode capacitance $V_R = 0\ \text{V}$, $f = 1\ \text{MHz}$	C_D	-	10	-	pF
Reverse recovery time $I_F = 200\ \text{mA}$, $I_R = 200\ \text{mA}$, $R_L = 100\ \Omega$, measured at $I_R = 20\ \text{mA}$	t_{rr}	-	1	-	ns

Test circuit for reverse recovery time

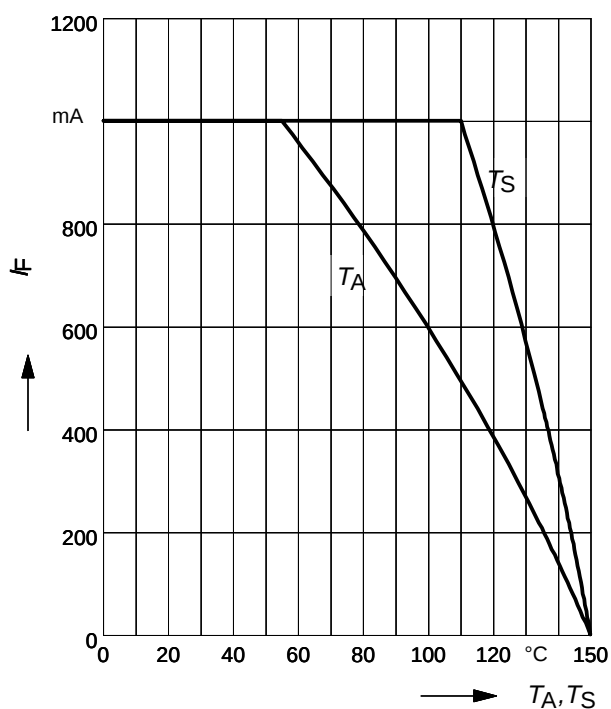


Pulse generator: $t_p = 100\text{ns}$, $D = 0.05$,
 $t_r = 0.6\text{ns}$, $R_i = 50\Omega$

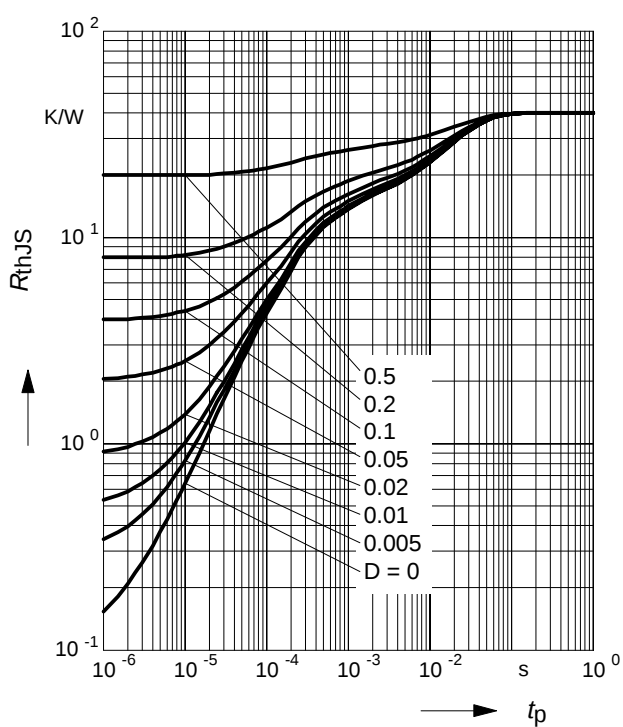
Oscilloscope: $R = 50\Omega$, $t_r = 0.35\text{ns}$,
 $C \leq 1\text{pF}$

Forward current $I_F = f(T_A^*; T_S)$

* Package mounted on epoxy

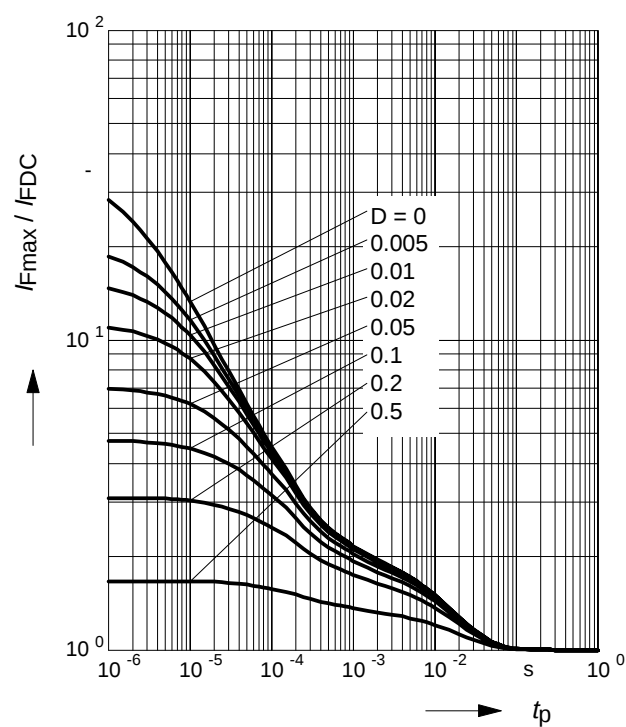


Permissible Pulse Load $R_{thJS} = f(t_p)$



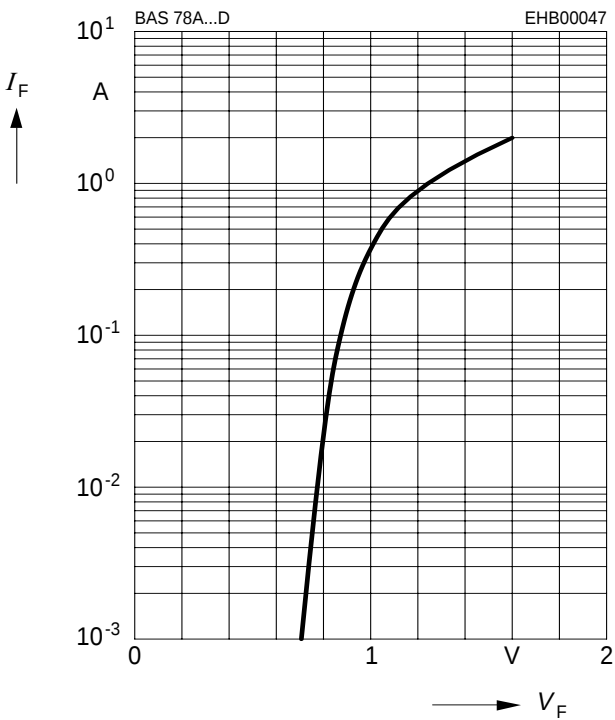
Permissible Pulse Load

$I_{Fmax} / I_{FDC} = f(t_p)$



Forward current $I_F = f(V_F)$

$T_A = 25^\circ\text{C}$



Reverse current $I_R = f(T_A)$

